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OTHER OFFICES

November 19, 2003

Assistant Commissioner

of Patents

Washington, D.C. 20231

Certificate

DEC 1 2 2003

of Correction

Re: CERTIFICATE OF CORRECTION

U. S. Letters Patent No. 6,632,704

Issued: Oct. 14, 2003

For: MOLDED FLIP CHIP PACKAGE

Inventor: Kumamoto et al. Our File No. 42390.P9482

Dear Sir:

Enclosed is the Certificate of Correction (two copies) for the above-referenced patent. This request for correction is made under rule 322 of the Rules of Practice and 35 U.S.C. Section 254.

Respectfully submitted,

BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Edwin H. Taylor

Reg. No. 25,129

EHT/gx Enclosures

## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

**PATENT NO.** : 6,632,704

DATED

: Oct. 14, 2003

**INVENTOR(S)**: Kumamoto et al.

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

In column 5, line 14, delete "fall", insert --full--.

In column 6, line 5, after "upper inner surface,", insert -- the lower mold portion having a lower inner surface, and--.

In column 6, line 8 and 9, delete "between the upper and lower mold portions", insert --that has an upper portion that includes the release film coated on the upper inner surface of the upper mold portion, and a lower inner surface that includes the lower inner surface of the lower mold--.

PATENT NO. <u>6,632,704</u>

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PATENT NO. <u>6,632,704</u>

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